



UM10566

User Manual for OM7941/BGA7130LTE

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User manual

Document information

Info	Content
Keywords	BGA7130, OM7941, evaluation kit, LTE-750, medium-power amplifier.
Abstract	This user manual describes the OM7941/BGA7130LTE evaluation kit for the BGA7130 medium-power amplifier.



Revision history

Rev	Date	Description
1	2012-09-11	Initial document

Contact information

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1. Introduction

The OM7941/BGA7130LTE customer evaluation kit enables the user to evaluate the performance of the BGA7130 medium-power amplifier. Please refer to the Data Sheet for information about the BGA7130 performance.

2. Contents of Customer Evaluation Kit

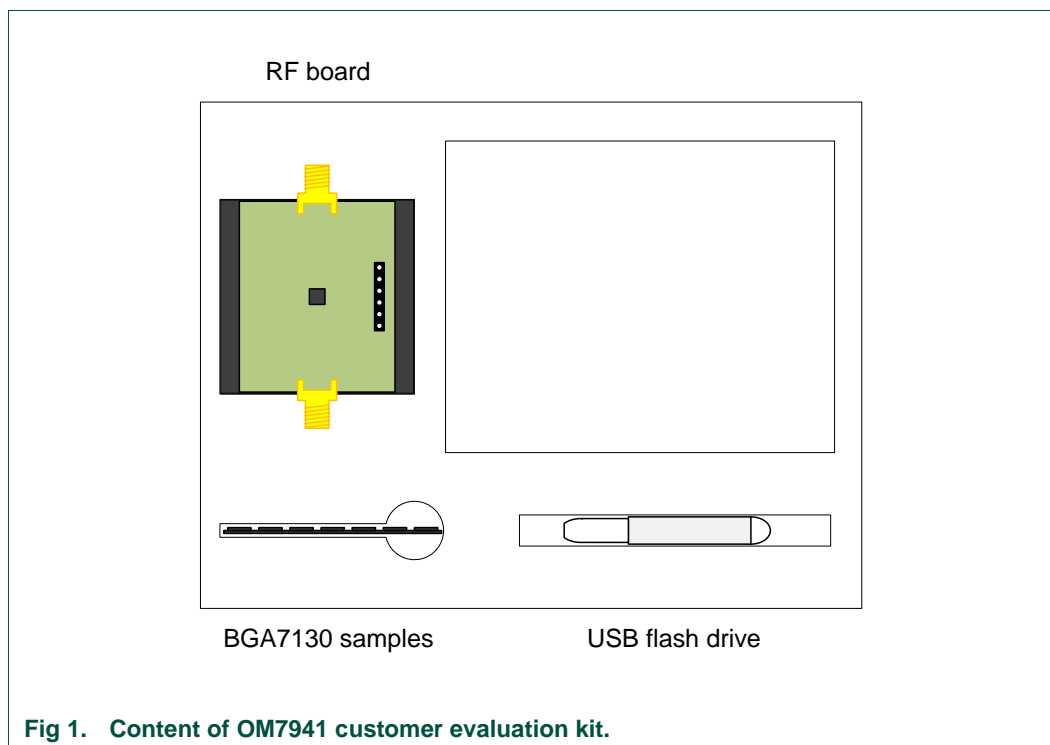


Fig 1. Content of OM7941 customer evaluation kit.

The evaluation kit contains the following items:

- RF board matched for LTE 750 MHz
- BGA7130 samples
- USB flash drive containing:
 - User manual OM7941/BGA7130LTE,
 - Device models,
 - Gerber files,
 - Data Sheet BGA7130
- ESD safe casing

3. BGA7130 samples

Several BGA7130 qualification samples are included. These samples are qualification

grade.

4. USB flash drive

Check website for latest updates, new application notes

5. LTE-750 RF board

The performance of the LTE-750 application is described in the BGA7130 datasheet. This section describes how to evaluate the provided board.

5.1 Interfaces

The interfaces are defined in Fig 2. RF input is located at the top side; RF output at the bottom side; ground, enable and supply should be provided through the molex connector on the right hand side.

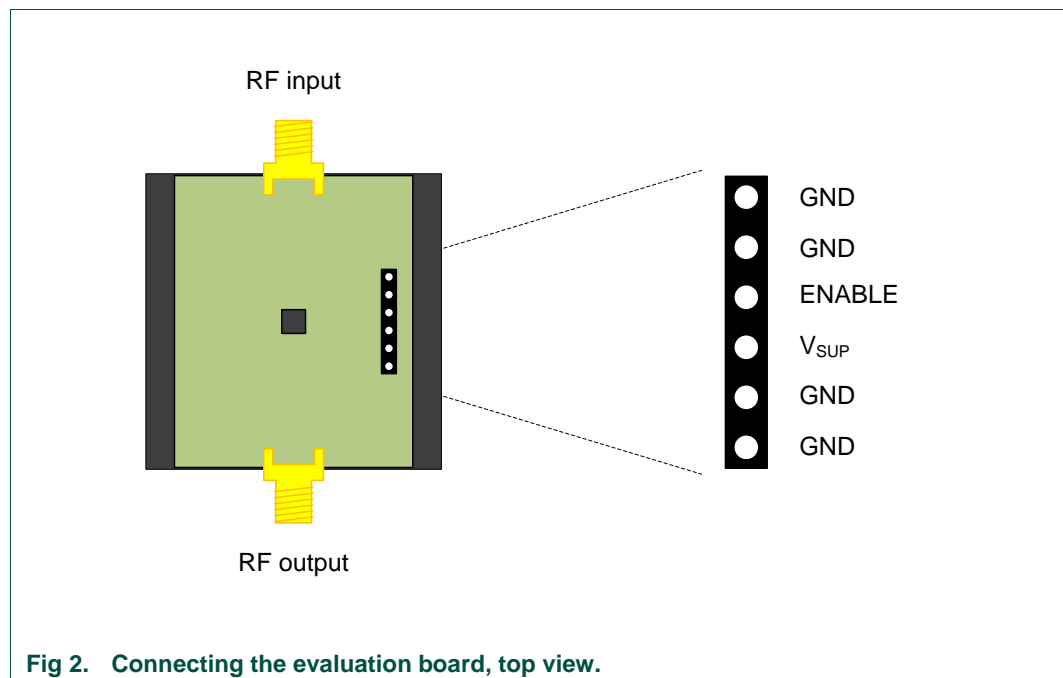


Fig 2. Connecting the evaluation board, top view.

5.2 Powering up

To power the BGA7130 evaluation board connect a GND molex pin to ground, the V_{SUP} molex pin to 5 V and the ENABLE molex pin also to a 5 V power supply.



It is good practice to avoid connecting the ENABLE pin to 5 V before V_{SUP} is connected to 5 V. If the voltage on pin ENABLE is higher than the voltage on pin V_{SUP} it might cause a current to flow through the ESD protection circuitry of the ENABLE pin. On the boards provided a current limiting resistor R2 has been placed, without it the ESD circuitry might be destroyed.

5.3 Powering down

Setting the pin ENABLE to a logic LOW (GND) will disable the device.

5.4 Evaluating the RF boards

5.4.1 S-parameters and output compression point

Both S-parameters and the output compression $P_{L(1dB)}$ point are measured with a network analyzer (NWA) as depicted in Fig 3.

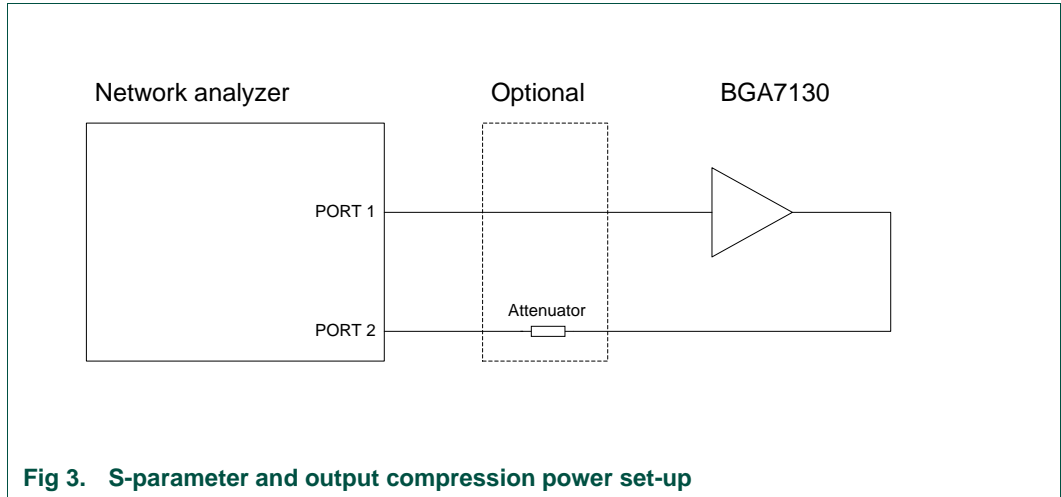


Fig 3. S-parameter and output compression power set-up

The $P_{L(1dB)}$ is measured by sweeping the input power, and observe where the S_{21} of the device has compressed 1 dB compared to the linear gain. For this measurement an input power calibration with a power head has to be performed, in order to accurately measure the input power. The output power of the device is calculated by

$$P_L \text{ (dBm)} = P_{in} \text{ (dBm)} + S_{21} \text{ (dB)}.$$

In order to prevent that output signal drives the receiver of the NWA into compression an attenuator can be inserted at the input of the NWA.

In order to maintain small signal conditions for the S-parameter measurements, an input power of -20 dBm is applied.

5.4.2 Output third order intercept point

The output third-order intercept point $IP3_O$ is a figure of merit for linearity (see Fig 4). The set-up (see Fig 5) is configured to achieve an accurate measurement of the $IP3_O$. After the signal generators, a low pass filter (LPF) and isolator is applied, before combining the two signals. This configuration gives best isolation between the generators, hence IMD3 levels of the input signal < -80 dBc can be measured.

Please refer to the Data Sheet for power levels and tone spacing.

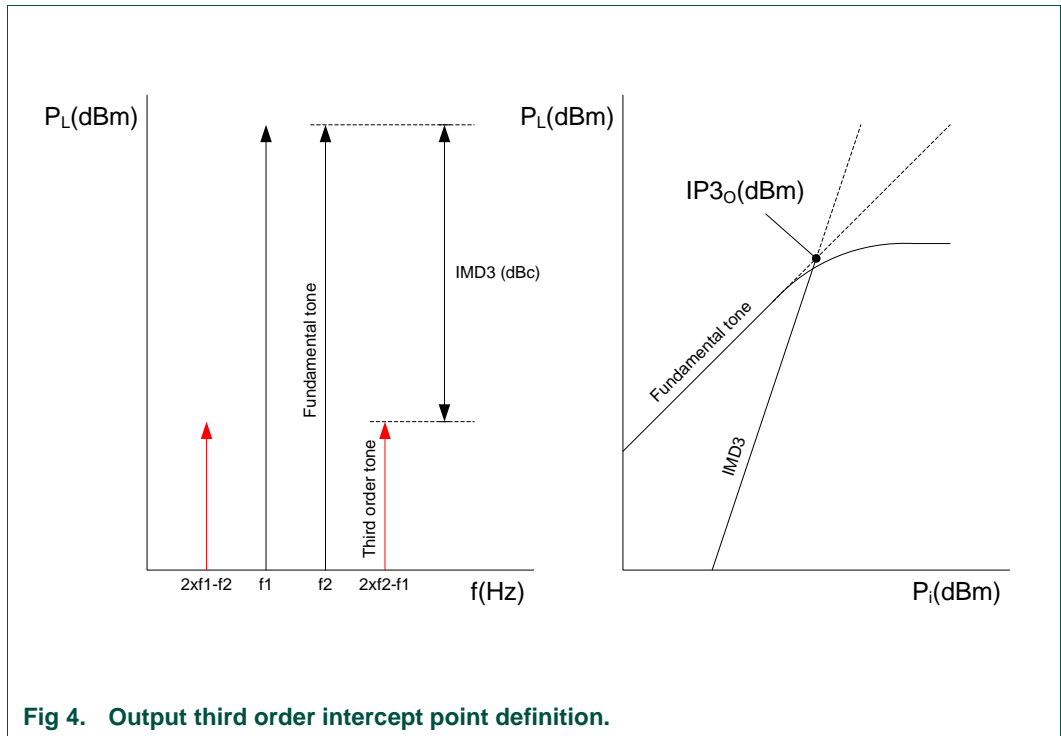


Fig 4. Output third order intercept point definition.

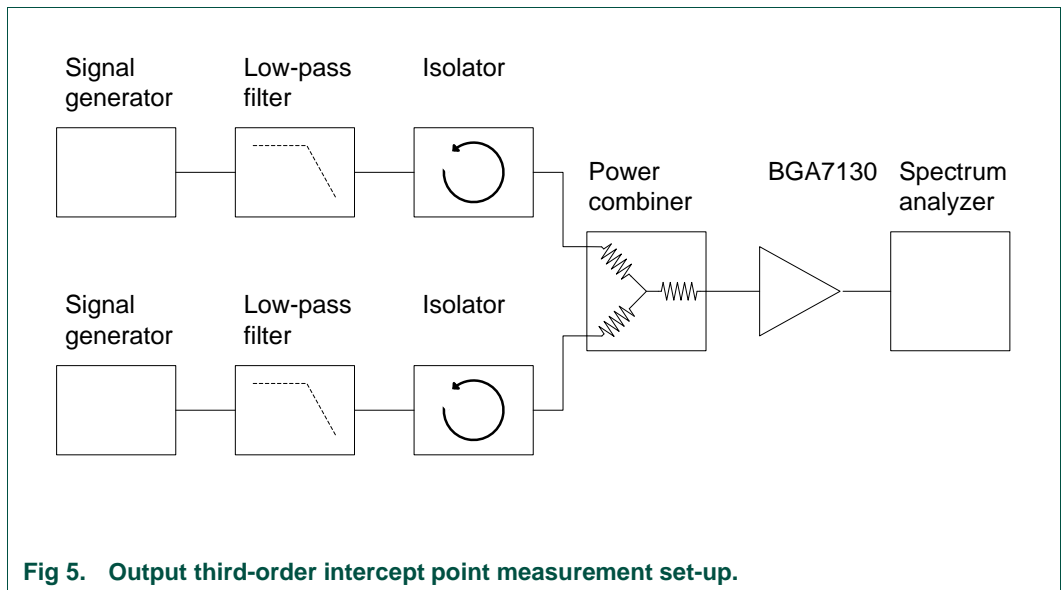
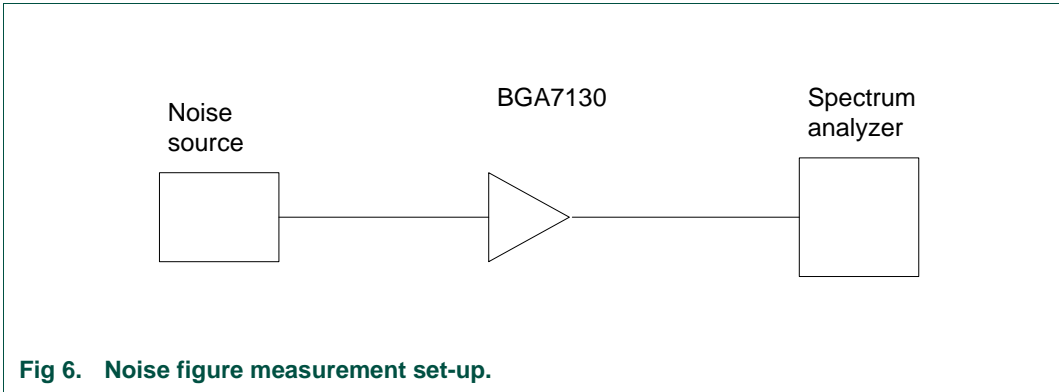


Fig 5. Output third-order intercept point measurement set-up.

5.4.3 Noise

The Noise Figure (NF) is measured with a calibrated noise source with a specified Excess Noise Ratio (ENR), and with a spectrum analyzer with a noise measurement option. The system is calibrated with this noise source, in order to measure accurate noise figures (see Fig 6).



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N/A

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